



Material Content Data Sheet



Sales Product Name		TLE4263-2ES		Issued		2. August 2019		
MA#		MA003914236						
Package		PG-DSO-8-27		Weight*		84.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.095	3.66	3.66	36618	36618
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.728	0.86		8609	
wire	non noble metal	copper	7440-50-8	29.548	34.96	35.87	349550	358697
	noble metal	gold	7440-57-5	0.147	0.17	0.17	1735	1735
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.11		1136
encapsulation	plastics	epoxy resin	-	4.418	5.23		52261	
	inorganic material	silicondioxide	60676-86-0	43.504	51.47	56.81	514658	568055
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8223	8223
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8571	8571
glue	plastics	epoxy resin	-	0.383	0.45		4525	
	noble metal	silver	7440-22-4	1.148	1.36	1.81	13576	18101
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com